



## Product Change Notification / RMES-26KYQW833

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### Date:

27-Sep-2021

### Product Category:

Analog to Digital Converters, Battery Management and Fuel Gauges - Battery Chargers, Digital Potentiometers

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4845 Initial Notice: Qualification of UTL3 as an additional assembly site for selected MCP42xx, MCP46xx, MCP738xx and MCP34xx device families available in 10L DFN (3x3x0.9mm) package.

### Affected CPNs:

[RMES-26KYQW833\\_Affected\\_CPN\\_09272021.pdf](#)

[RMES-26KYQW833\\_Affected\\_CPN\\_09272021.csv](#)

### Notification Text:

**PCN Status:** Initial notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of UTL3 as an additional assembly site for selected MCP42xx, MCP46xx, MCP738xx and MCP34xx device families available in 10L DFN (3x3x0.9mm) package.

### Pre and Post Change Summary:

|  | Pre Change | Post Change |
|--|------------|-------------|
|  |            |             |

| Assembly Site             | UTAC Thai Limited<br>(UTL-1) LTD.<br>(NSEB) | UTAC Thai Limited<br>(UTL-1) LTD.<br>(NSEB) | UTAC Thai Limited<br>(UTL-3)<br>(UTL3) |
|---------------------------|---|---|--|
| Wire material             | Au  | Au  | Au                                     |
| Die attach material       | 8600  | 8600  | 8600                                   |
| Molding compound material | G700LTD                                     | G700LTD                                     | G700LTD                                |
| Lead frame material       | C194  | C194  | C194                                   |

**Impacts to Data Sheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability and productivity by qualifying UTL3 as an additional assembly site

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** January 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

|                          | September 2021 |    |    |    |    | > | January 2022 |    |    |    |    |
|--------------------------|----------------|----|----|----|----|---|--------------|----|----|----|----|
|                          | 36             | 37 | 38 | 39 | 40 |   | 01           | 02 | 03 | 04 | 05 |
| Workweek                 |                |    |    |    |    |   |              |    |    |    |    |
| Initial PCN Issue Date   |                |    |    |    | X  |   |              |    |    |    |    |
| Qual Report Availability |                |    |    |    |    |   |              |    | X  |    |    |
| Final PCN Issue Date     |                |    |    |    |    |   |              |    | X  |    |    |

**Method to Identify Change:** Traceability code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History: September 27, 2021:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

[PCN\\_RMES-26KYQW833\\_Qual\\_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.



**MICROCHIP**

# **QUALIFICATION PLAN SUMMARY**

**PCN #: RMES-26KYQW833**

**Date:  
September 16, 2021**

**Qualification of UTL3 as an additional assembly site for selected MCP42xx, MCP46xx, MCP738xx and MCP34xx device families available in 10L DFN (3x3x0.9mm) package.**

**Purpose: Qualification of UTL3 as an additional assembly site for selected MCP42xx, MCP46xx, MCP738xx and MCP34xx device families available in 10L DFN (3x3x0.9mm) package.**

|                   |  |                     |
|-------------------|--|---------------------|
| <u>Misc.</u>      | Assembly site  | UTL3                |
|                   | BD Number  | TBD                 |
|                   | MP Code (MPC)  | D5AL2YE2XR05        |
|                   | Part Number (CPN)  | MCP4262T-502E/MF    |
|                   | MSL information  | MSL-1 @260C         |
|                   | Assembly Shipping Media (T/R, Tube/Tray)                   | T/R                 |
|                   | Base Quantity Multiple (BQM)                               | 3,300 units         |
|                   | Reliability Site   | MTAI                |
|                   | CCB No.  | 4845                |
| <u>Lead-Frame</u> | Paddle size  | 71x102 mil          |
|                   | DAP Surface Prep   | Ag on lead only     |
|                   | Treatment  | Yes (Rough inhouse) |
|                   | Process  | Etched              |
|                   | Lead-lock Design (Locking Hole, Half Etched, Dimple, etc.) | U-groove            |
|                   | Part Number  | FR0040              |
|                   | Lead frame Thickness                                       | 8 mils              |
|                   | Lead Plating   | Matte Tin           |
|                   | Strip Size   | 250x70 mm.          |
|                   | Strip Density  | 1170 units/strip    |
| <u>Bond Wire</u>  | Material   | Au                  |
| <u>Die Attach</u> | Part Number  | 8600                |
|                   | Conductive   | Yes                 |
| <u>MC</u>         | Part Number  | G700LTD             |
| <u>PKG</u>        | PKG Type   | DFN                 |
|                   | Pin/Ball Count   | 10                  |
|                   | PKG width/size   | 3x3x0.9mm           |

| Test Name  | Conditions   | Sample Size   | Min. Qty of Spares per Lot (should be properly marked) | Qty of Lots | Total Units | Fail Accept Qty  | Est. Dur. Days | ATE Test Site | REL Test Site | Special Instructions   |
|--|--|---|--|-------------|-------------|------------------|----------------|---------------|---------------|--|
| Wire Bond Pull - WBP                                 | Mil. Std. 883-2011   | 5   | 0  | 1           | 5           | 0 fails after TC | 5              |               | UTL3          | 30 bonds from a min. 5 devices.  |
| Wire Bond Shear - WBS                                | CDF-AEC-Q100-001   | 5   | 0  | 1           | 5           | 0                | 5              |               | UTL3          | 30 bonds from a min. 5 devices.  |
| Physical Dimensions                                  | Measure per JESD22 B100 and B108   | 10  | 0  | 3           | 30          | 0                | 5              |               | UTL3          |  |
| External Visual                                      | Mil. Std. 883-2009/2010  | All devices prior to submission for qualification testing | 0  | 3           | ALL         | 0                | 5              |               | UTL3          |  |
| Preconditioning - Required for surface mount devices | +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C.<br><br>MSL1 @ 260C | 231   | 15   | 3           | 738         | 0                | 15             | MTAI          | MTAI          | Spares should be properly identified.<br>77 parts from each lot to be used for HAST, uHAST, Temp Cycle test. |
| HAST   | +130°C/85% RH for 96 hours<br><br>Electrical test pre and post stress at +25°C and hot temp.   | 77  | 5  | 3           | 246         | 0                | 10             | MTAI          | MTAI          | Spares should be properly identified.<br>Use the parts which have gone through Pre-conditioning.             |

| Test Name  | Conditions   | Sample Size | Min. Qty of Spares per Lot (should be properly marked) | Qty of Lots | Total Units | Fail Accept Qty | Est. Dur. Days | ATE Test Site | REL Test Site | Special Instructions   |
|------------|--|-------------|--|-------------|-------------|-----------------|----------------|---------------|---------------|--|
| UHAST      | +130°C/85% RH for 96 hrs<br><br>Electrical test pre and post stress at +25°C   | 77          | 5  | 3           | 246         | 0               | 10             | MTAI          | MTAI          | Spares should be properly identified.<br>Use the parts which have gone through Pre-conditioning. |
| Temp Cycle | -65°C to +150°C for 500 cycles.<br><br>Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. | 77          | 5  | 3           | 246         | 0               | 15             | MTAI          | MTAI          | Spares should be properly identified.<br>Use the parts which have gone through Pre-conditioning. |

Affected Catalog Part Numbers (CPN)

MCP4232-502E/MF  
MCP4232-103E/MF  
MCP4232-104E/MF  
MCP4232-503E/MF  
MCP4242-502E/MF  
MCP4242-103E/MF  
MCP4242-104E/MF  
MCP4242-503E/MF  
MCP4262-502E/MF  
MCP4262-103E/MF  
MCP4262-104E/MF  
MCP4262-503E/MF  
MCP4252-502E/MF  
MCP4252-103E/MF  
MCP4252-104E/MF  
MCP4252-503E/MF  
MCP4232T-502E/MF  
MCP4232T-103E/MF  
MCP4232T-104E/MF  
MCP4232T-503E/MF  
MCP4242T-502E/MF  
MCP4242T-103E/MF  
MCP4242T-104E/MF  
MCP4242T-503E/MF  
MCP4262T-502E/MF  
MCP4262T-103E/MF  
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MCP4252T-502E/MF  
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MCP4632T-502E/MF  
MCP4632T-103E/MF  
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MCP4652T-103E/MF  
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MCP4652T-503E/MF  
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MCP4662T-103E/MF



MCP4662T-104E/MF  
MCP4662T-503E/MF  
MCP73833-6SI/MF  
MCP73833-AMI/MF  
MCP73833-B6I/MF  
MCP73833-BZI/MF  
MCP73833-CNI/MF  
MCP73833-DZI/MF  
MCP73833-FCI/MF  
MCP73833-G8I/MF  
MCP73833-GPI/MF  
MCP73833-HAI/MF  
MCP73833-NVI/MF  
MCP73833-YAI/MF  
MCP73834-6SI/MF  
MCP73834-B6I/MF  
MCP73834-CNI/MF  
MCP73834-FCI/MF  
MCP73834-G8I/MF  
MCP73834-GPI/MF  
MCP73834-NVI/MF  
MCP73834-YAI/MF  
MCP73833T-6SI/MF  
MCP73833T-AMI/MF  
MCP73833T-B6I/MF  
MCP73833T-BZI/MF  
MCP73833T-CNI/MF  
MCP73833T-DZI/MF  
MCP73833T-FCI/MF  
MCP73833T-G8I/MF  
MCP73833T-GPI/MF  
MCP73833T-HAI/MF  
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MCP73838T-FJI/MF  
MCP73838T-NVI/MF  
MCP3423-E/MF  
MCP3427-E/MF  
MCP3423T-E/MF  
MCP3427T-E/MF